

Mechanical Support System for a Thin Package

Abstract of the Disclosure

An electronic package includes an IC, such as a die, mounted onto one side
5 of a thin interposer and a pin carrier mounted to an opposing side of the interposer.
The pin carrier includes a cavity underneath the die. The cavity allows capacitors,
or other electronic components, to be mounted against the interposer beneath the
die. The cavity in the pin carrier is filled with an encapsulant to mechanically
support the thin interposer in the area of the cavity during operation of an electronic
10 system that includes the package.

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